

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0.00195	1.22	0.02928
	Doped silicon	Silicon (Si)	7440-21-3	0.1579	98.78	2.37072
		<b>Subtotal</b>		<b>0.15985</b>	<b>100</b>	<b>2.4</b>
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01145	10.0	0.17187
	Silver alloy	Silver (Ag)	7440-22-4	0.00229	2.0	0.03437
	Lead alloy	Lead (Pb)	7439-92-1	0.10074	88.0	1.51248
		<b>Subtotal</b>		<b>0.11448</b>	<b>100</b>	<b>1.71872</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.28029	100.0	4.20829
		<b>Subtotal</b>		<b>0.28029</b>	<b>100</b>	<b>4.20829</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00979	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00652	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00979	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03588	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.56008	99.81	488.8594
		<b>Subtotal</b>		<b>32.62206</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32303	100.0	4.85
		<b>Subtotal</b>		<b>0.32303</b>	<b>100</b>	<b>4.85</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.32002	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.86523	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.4655	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.1995	0.3	2.99532
	Polymer	Epoxy resin system		6.65003	10.0	99.844
		<b>Subtotal</b>		<b>66.50028</b>	<b>100</b>	<b>998.44</b>
		<b>Total</b>		<b>99.99999</b>	<b>100</b>	<b>1501.40702</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.